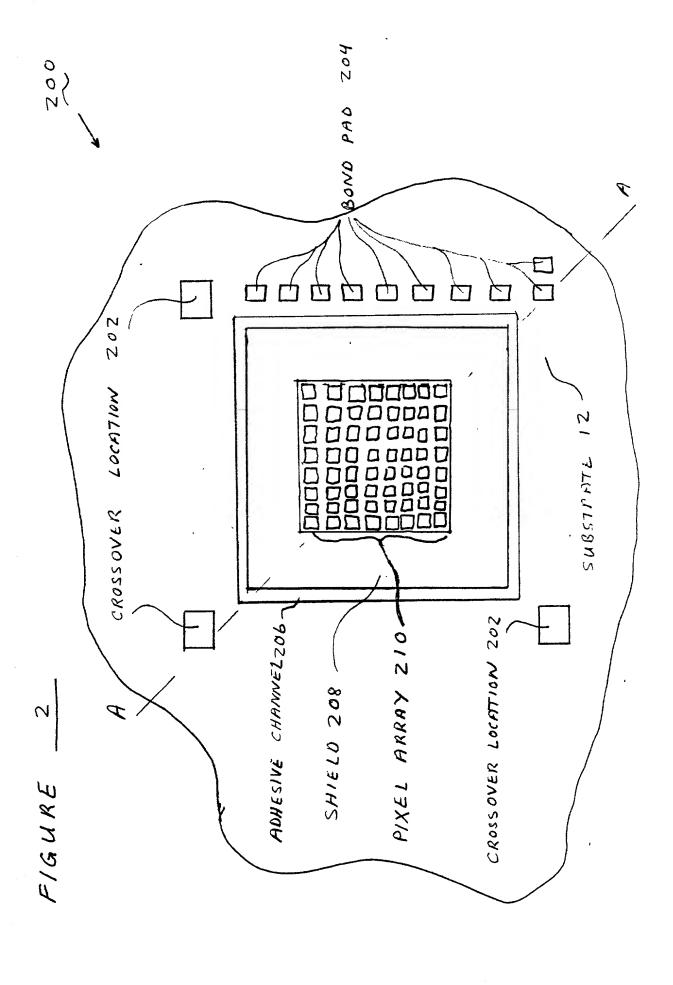
000 FIGURE

SAP 18 2 MICRONS GASKET WIDTH 20 - 500 MICRONS -ADHESIVE 16 TOP SHEET 14 SUBSTRATE 12 CONOUCTIVE LAYER 15



W FIGURE

INTERMETAL DIELECTRIC 312-BOND PAD 2047 INTERMETAL DIELECTRIC 310 PASSIVATION DIELECTRIC 306 ADHESIVE 16-3/4 PIXEL ARKAY 210 208 ] h LC MATERIAL 304-TOP SHEET 14 -802 0791HS CE11 GAP 3167 3/4 3/4 METAL LAYER 308 SUBSTRATE 12 AOHESIVE CHANNEL 206-CAP 3/8~ CONOUCTIVE CONDUCTIVE CROSSOVER MATERIAL CROSSOVER LOCATION 302 --202

